# 2019 22nd European Microelectronics and Packaging Conference & Exhibition (EMPC 2019)

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# 2019 22nd European Microelectronics and Packaging Conference & Exhibition (EMPC)

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# Tuesday 16<sup>th</sup> September to Thursday 19<sup>th</sup> September Released for IEEE-Xplore: ISBN 978-0-9568086-6-0

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